Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **INPUT VOLTAGE (VIN)**
2. **TEMPERATURE TRANDUCER OUTPUT VOLTAGE (TEMP)**
3. **GND**
4. **TRIM**
5. **OUTPUT VOLTAGE (VOUT)**

**.074”**

**1 5**

**2 3 4**

**.048”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004 x .004”**

**Backside Potential: GND**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .048” X .074” DATE: 8/25/21**

**MFG: ANALOG DEVICES THICKNESS .020” P/N: REF01NBC**

**DG 10.1.2**

#### Rev B, 7/1